

Title (en)
ELECTRONIC DEVICES HAVING THERMODYNAMIC ENCAPSULANT PORTIONS PREDOMINATING OVER THERMOSTATIC ENCAPSULANT PORTIONS

Title (de)
ELEKTRONISCHE ANORDNUNG MIT THERMODYNAMISCHEN VERPACKUNGSTEILEN, VORHERSCHEND ÜBER THERMOSTATISCHE VERPACKUNGSTEILE

Title (fr)
DISPOSITIFS ELECTRONIQUES AYANT DES PARTIES THERMODYNAMIQUES ENCAPSULANTES PREDOMINANT SUR DES PARTIES THERMOSTATIQUES ENCAPSULANTES

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Application
EP 99905475 A 19990126

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• US 7270098 P 19980127
• US 7630698 P 19980227

Abstract (en)
[origin: WO9938196A2] A method for and an electronic device comprising a circuit board having a contact and an integrated circuit chip of a given physical geometry, the chip having a lead electrically connected in hot-soldered relation to the contact, the chip having a protective composition congruent therewith and adhering thereto, the composition comprising a resin having thermostatic crystalline polymer chain portions and thermodynamic polymer chain portions, the thermodynamic polymer chain portions being present in such proportion that they expansively absorb the heat of the hot solder connection in preference to the thermostatic crystalline polymer chain portions. Thus, the protective composition remains congruent with and adheres to the physical geometry of the chip through a soldering cycle.
[origin: WO9938196A2] An electronic device (10) and a method for assembling the device (10) comprising a circuit board (14) having contacts (24, 26) and an integrated circuit chip (12) of a given physical geometry, the chip (12) having leads (18, 22) electrically connected in hot-solder relation to the contacts (24, 26) the chip (12) having a protected composition congruent therewith and adhering thereto, the composition comprising a resin (28) having thermostatic crystalline polymer chain portions and thermodynamic polymer chain portions, the thermodynamic chain portions being present in such proportion that they expansively absorb the heat of the hot-solder connection in preference to the thermostatic crystalline polymer chain portions. Thus, the protective composition remains congruent with and adheres to the physical geometry of the chip (12) through a soldering cycle.

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Citation (search report)
• [X] US 4130546 A 19781219 - GOTO KAZUO, et al
• [X] WO 9515579 A1 19950608 - GIAT IND SA [FR], et al
• [X] DE 19513914 A1 19951019 - VAGNONE & BOERI [IT]
• See references of WO 9938196A2

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